

SEMICONDUCTOR®

# FMKA130

#### Features

- Compact Surface Mount with J-bend Leads (SMA)
- 1.2 Watt Power Dissipation Package
- 1.0 Ampere, Forward Voltage Less than 600mV



SMA (DO-214AC) Color Band Denotes Cathode Mark: A13

# **Schottky Rectifier**

| Absolute Maximum Ratings * | * | $T_A = 25^{\circ}C$ unless otherwise noted |
|----------------------------|---|--|
|----------------------------|---|--|

| Symbol             | Parameter  | Value       | Units<br>V |  |
|--------------------|--|-------------|------------|--|
| V <sub>RRM</sub>   | Maximum Repetitive Reverse Voltage                         | 130         |            |  |
| I <sub>F(AV)</sub> | Average Rectified Forward Current @ T <sub>L</sub> = 120°C | 1.0         | А          |  |
| FSM                | Non-repetitive Peak Forward Surge Current                  | 30          | A          |  |
| T <sub>STG</sub>   | Storage Temperature Range                                  | -65 to +150 | °C         |  |
| TJ                 | Operating Junction Temperature                             | -65 to +125 | °C         |  |

\* These ratings are limiting values above which the serviceability of the diode may be impaired.

## **Thermal Characteristics**

| Symbol                | Parameter   | Value | Units |
|-----------------------|---|-------|-------|
| $R_{	extsf{	heta}JL}$ | Thermal Resistance Junctionto Lead<br>(Half wave, single phase, 60 Hz | 9.6   | °C/W  |

## Electrical Characteristics T<sub>A</sub>=25°C unless otherwise noted

| Symbol         |                 | Parameter                                    | Min. | Max. | Units |
|----------------|-----------------|--|------|------|-------|
| V <sub>F</sub> | Forward Voltage | @ I <sub>F</sub> = 1.0A                      |      | 550  | mV    |
| I <sub>R</sub> | Reverse Leakage | $V_R = 30V$                                  |      | 1.0  | mA    |
|                |                 | V <sub>R</sub> = 30V, T <sub>A</sub> = 100°C |      | 10   | mA    |

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|--------------------------|---------------------------|---|
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